



# Embedded Systems Week

[www.esweek.org](http://www.esweek.org)

October 4 – October 9, 2026

Barcelona, Spain



## Call for Papers, Workshops, Tutorials, Special Sessions

• CASES • CODES • EMSOFT • MEMOCODE • Workshops • Tutorials •

### About Embedded Systems Week (ESWEEK)

Embedded Systems Week (ESWEEK) is the premier event covering all aspects of hardware and software design for intelligent and connected embedded, edge and cyber-physical systems. By bringing together three leading international conferences (CASES, CODES, EMSOFT), one symposium (MEMOCODE), and several workshops and tutorials, ESWEEK allows attendees to benefit from a wide range of topics covering the state of the art in embedded systems research and development.

### One Registration, three Conferences!

Registered attendees can attend sessions in any of the ESWEEK conferences (CASES, CODES, EMSOFT). Please note that tutorials, symposia (MEMOCODE), and workshops may use separate registration.

#### Journal Track:

Abstract Submission: March 23, 2026

Full Paper Submission: March 30, 2026 (firm)

Notification of Acceptance: July 17, 2026

#### Late Breaking and Work-in-Progress Tracks:

Paper Submission: June 5, 2026 (firm)

Notification of Acceptance: July 17, 2026

**Proposals of Workshops, Tutorials, Education Classes, and Special Sessions: March 30, 2026**

**All submissions are due by midnight, AOE.**

**CASES**

IEEE/ACM International Conference on  
Compilers, Architectures, and  
Synthesis for Embedded Systems

IEEE/ACM CASES is a premier forum where researchers, developers and practitioners exchange information on the latest advances in compilers and architectures for high-performance, low-power embedded systems. The conference has a long tradition of showcasing leading edge research in embedded processor, memory, interconnect, storage architectures and related compiler techniques targeting performance, power, predictability, security, reliability issues for both traditional and emerging application domains. In addition, we invite innovative papers that address design, synthesis, and optimization challenges in heterogeneous and accelerator-rich architectures.

IEEE/ACM International Conference  
on Co-Design of Embedded Systems



The IEEE/ACM International Conference on Co-Design of Embedded Systems (CODES) – previously known as CODES+ISSS – is the premier event in system-level design, modeling, analysis, and implementation of modern embedded, edge and cyber-physical systems, from system-level specification and optimization down to system synthesis of multi-processor hardware/software implementations. The conference is a forum bringing together academic research and industrial practice for all aspects related to system-level and hardware/software co-design.

Symposia

Tutorials

Workshops

**EMSOFT**

IEEE/ACM International Conference on  
Embedded Software

IEEE/ACM EMSOFT brings together researchers and developers from academia, industry, and government to advance the science, engineering, and technology of embedded software development. Since 2001, EMSOFT has been the premier venue for cutting-edge research in the design and analysis of software that interacts with physical processes, with a long-standing tradition for results on cyber-physical systems, which compose computation, networking, and physical dynamics.

IEEE/ACM International Symposium  
on Formal Methods and Models for  
System Design



IEEE/ACM MEMOCODE focuses on formal methods and models for developing computer systems and their components. MEMOCODE's objective is to emphasize the importance of models and methodologies in correct system design and development.

Keynotes

**Journal-Integrated Publication Model:** All full papers accepted in one of the three conferences will be published in **IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)**. All late-breaking papers accepted in one of the three conferences will be published in **IEEE Embedded Systems Letters (ESL)**.

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## Paper Process

ESWEEK 2026 has two publication venues. **(1) Journal Track:** Full-length papers describing mature work limited to 12 pages in IEEE double-column format. Accepted papers will be published in *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)* after two stages of review. **(2) Late Breaking (LB) Result Track:** LB papers describing complete and mature work, limited to 4 pages in IEEE double-column format. Accepted papers will be published in *IEEE Embedded Systems Letters (ESL)* after one stage of review. These two venues are mutually exclusive. For more information on the publishing process, please refer to <http://www.esweek.org/author-information>.

## Workshops, Tutorials, Special Sessions

### Call for Workshop Proposals

ESWEEK 2026 will host several workshops on October 8-9 and is soliciting proposals for new and recurring workshops. Workshops can be from a half-day to two-days long. We invite workshop proposals on any topic related to the broad set of research and education in embedded systems.

### Call for Tutorial Proposals

ESWEEK 2026 is looking for high-quality tutorials that will take place on Sunday, October 4, 2026. Tutorials on all topics related to embedded system design, analysis, and development are welcome. Tutorials can be either half/full-day, lecture style or hands-on.

### Call for Education Proposals

ESWEEK 2026 will host several education lectures *virtually* on Friday October 2 and is soliciting proposals for such lectures. We invite you to submit education proposals on any topic related to all aspects of design, validation, manufacturing of embedded systems.

### Call for Special Session Proposals

We invite you to submit special session proposals on any topic relevant to the broad areas of interest of ESWEEK. The special session should cover a topic that is contemporary, hot, and **complementary to the regular sessions** to generate enthusiasm among the ESWEEK participants.

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